

**IPC-4592**  
**2022 - August**  
**Requirements for Printed**  
**Electronics Functional**  
**Dielectric Materials**

*An international standard developed by IPC*



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- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase cycle time
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IPC-4592

# Requirements for Printed Electronics Functional Dielectric Materials

Developed by the Printed Electronics Functional Dielectric Materials Task Group (D-63A) of the Printed Electronics Committee (D-60) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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## Acknowledgment

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IPC recognizes this A-Team for their exceptional leadership and effort in the development of this standard.

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# Requirements for Printed Electronics Functional Dielectric Materials

## 1 SCOPE

This standard establishes the classification system and the qualification and quality conformance requirements for functional dielectric materials used in printed electronics applications. The intended applications include but are not limited to dielectric materials as protective dielectric or insulator/insulation layer(s), capacitive layer(s), crossovers and encapsulant(s) for devices in printed electronics systems.

**1.1 Purpose** The purpose of this standard is to provide a detailed list of parameters and their characterization methods for the intended application of functional dielectric materials used in printed electronics.

**1.2 Classification** IPC standards recognize that electrical and electronic assemblies are subject to classification, by intended end-item use. Three general end-product classes have been established to reflect differences in manufacturing complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

### **CLASS 1** General Electronic Products

Includes products suitable for applications where the major requirement is function of the complete assembly.

### **CLASS 2** Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

### **CLASS 3** High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

**1.3 Measurement Units** All dimensions and tolerances in this specification are expressed in hard SI (metric) units and bracketed soft imperial [inch] units. Users of this specification are expected to use metric dimensions. All dimensions  $\geq 1$  mm [0.0394 in] will be expressed in millimeters and inches. All dimensions  $< 1$  mm [0.0394 in] will be expressed in micrometers and microinches.

**1.4 Definition of Requirements** The words **shall** or **shall not** are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.

The word “should” reflect recommendations and is used to reflect general industry practices and procedures for guidance only.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this Standard. The text takes precedence over the figures.

**1.5 Process Control Requirements** The primary goal of process control is to continually reduce variation in the processes, products, or services to provide products or processes meeting or exceeding user requirements. Process control tools such as IPC-9191 or other user-approved system may be used as guidelines for implementing process control.

A documented process control system, if established, **shall** define process control and corrective action limits.

This may or may not be a statistical process control system. The use of statistical process control (SPC) is optional and should be based on factors such as design stability, lot size, production quantities and the needs of the manufacturer (see 4.12).

When a decision or requirement is to use a documented process control system, failure to implement process corrective action and/or the use of continually ineffective corrective actions **shall** be grounds for disapproval of the process and associated documentation.

**1.6 Order of Precedence** The contract **shall** take precedence over this standard, referenced standards and drawings.

In the event of conflict, the following order of precedence applies:

- 1) Procurement as agreed and documented between user and supplier.
- 2) Master drawing, design brief or tech pack reflecting the user's detailed requirements.
- 3) When invoked by the customer or per contractual agreement, this standard.

When documents other than this standard are cited, the order of precedence **shall** be defined in the procurement documents. The user can specify alternate acceptance criteria.